

Sterne Kessler
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December 24, 2002

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Commissioner for Patents
Washington, D.C. 20231

Art Unit: 2823

Re: U.S. Patent Application
Appl. No. 09/753,664; Filed: January 4, 2001
For: **High Density Metal Capacitor Using Via Etch Stopping Layer as Field Dielectric in Dual-Damascene Interconnect Process**
Inventor: Liming Tsau
Our Ref: 1875.0230000

Sir:

Transmitted herewith for appropriate action are the following documents:

1. Request for Reconsideration Under 37 C.F.R. § 1.111; and
2. Return post card.

It is respectfully requested that the attached postcard be stamped with the date of filing of these documents, and that it be returned to our courier. In the event that extensions of time are necessary to prevent abandonment of this patent application, then such extensions of time are hereby petitioned.

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The U.S. Patent and Trademark Office is hereby authorized to charge any fee deficiency, or credit any overpayment, to our Deposit Account No. 19-0036.

Respectfully submitted,

STERNE, KESSLER, GOLDSTEIN & FOX P.L.L.C.



Donald J. Featherstone
Attorney for Applicant
Registration No. 33,876

Enclosures

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